



OLED SPECIFICATION

Model No:

REX006448AYPP3N00000

New Product only for reference

CUSTOMER:

APPROVED BY	
PCB VERSION	
DATE	

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY
Release DATE:		100	



1. Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0	2016/12/08		First release
Α	2019/09/02		Modify Precautions in
			use of OLED Modules



Contents

- 1.General Specification
- 2. Module Classification Information
- 3.Interface Pin Function
- 4. Contour Drawing & Block Diagram
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- 8.OLED Lifetime
- 9.Reliability
- 10.Inspection specification
- 11.Precautions in use of OLED Modules



1.General Specification

The Features is described as follow:

■ Module dimension: 18.46 × 18.10 × 1.3 mm

■ Active area: 13.42 × 10.06 mm

■ Dot Matrix: 64 x 48 Dots

■ Pixel size: 0.185 x 0.185 mm

■ Pixel pitch: 0.210 × 0.210 mm

■ Display Mode: Passive Matrix

■ Drive Duty: 1/48 Duty

■ Display Color: Yellow

■ IC: SSD1306BZ



2.Module Coding System

1	2	3	4	5	6	7	8	9	10	11	12	13	14
R	Е	Х	006448	Α	Υ	Р	Р	3	N	0	0	0	00

1	Brand: Raystar Op	tronics Inc.		
2	E: OLED			Λ
3	Display Type : C→0	Character, G→Graph	nic , T→TAB ,X→COG	, H→COG (with Frame)
4	Dot Matrix: 64*48			
5	Series			1 7
		A: Amber	R: Red	C : Full Color
	Emitting Color	B: Blue	W: White	
6	Emitting Color	G: Green	Y: Yellow	
		S: Sky Blue	X : Dual Color	
7	Dolorizor	P: With Polarizer;	N: Without Polarizer	
7	Polarizer	A: Anti-glare Pola	ırizer	
8	Display Mode	P: Passive Matrix	; N : Active Matrix	
9	Driver Voltage	3:3.0~3.3V ; 5	5 : 5.0V	
10	Touch Panel	N: Without touch	panel; T: With touch pan	nel
		0 : Standard 1 : Sunlight Reada	able	
11	Product type	2 : Transparent Ol		
		3 : Flexible OLED		
		4 : OLED Lighting		
	4	0 : Standard		
12	Inspection Grade	2 : B grade		
'	mopeonon Grade	C: Automotive gra		
		Y : Consumer grad		
13	Interface	0 : Default ; F : FF	PC ; H:Hot bar ; D:De	emo Kit
14	Serial No.	Serial number(00~	·ZZ)	





3.Interface Pin Function

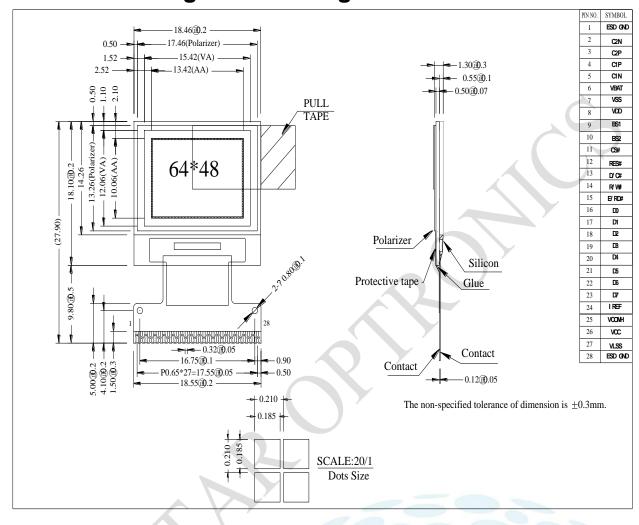
No.	Symbol	Function			
1	ESD-GND	It should be connected to ground.			
2	C2N	Positive Terminal of the Flying Inverting Capacitor Negative Terminal of			
3	C2P	the Flying Boost Capacitor The charge-pump capacitors are required			
4	C1P	between the terminals. They must be floated when the converter is not			
5	C1N	used.			
6	VBAT	Power Supply for DC/DC Converter Circuit This is the power supply pin for the internal buffer of the DC/DC voltage converter. It must be connected to external source when the converter is used. It should be connected to VDD when the converter is not used.			
7	VSS	This is a ground pin.			
8	VDD	Power supply pin for core logic operation.			
9	BS1	MCU bus interface selection pins.			
10	BS2	Table : MCU Bus Interface Pin Selection SSD1306B I ² C 6800-parallel 8080-parallel 4-wire Serial interface BSO 0 0 0 0 0 0 BS1 1 0 1 0 0 0 0 0 0			
		BS2 0 1 1 0			
11	CS#	Chip Select This pin is the chip select input. The chip is enabled for MCU communication only when CS# is pulled low.			
12	RES#	Power Reset for Controller and Driver This pin is reset signal input. When the pin is low, initialization of the chip executed.			
13	D/C#	This is Data/Command control pin. When it is pulled HIGH (i.e. connect to VDD), the data at D[7:0] is treated as data. When it is pulled LOW, the data at D[7:0] will be transferred to the command register. In I2C mode, this pin acts as SA0 for slave address selection. When 3-wire serial interface is selected, this pin must be connected to VSS.			
14	R/W#	This is read / write control input pin connecting to the MCU interface. When interfacing to a 6800-series microprocessor, this pin will be used at Read/Write (R/W#) selection input. Read mode will be carried out when this pin is pulled HIG (i.e. connect to VDD) and write mode when LOW.			



		_
15	E/RD#	When interfacing to a 6800-series microprocessor, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled HIGH (i.e. connect to VDD) and the chip is selected. When connecting to an 8080-series microprocessor, this pin receives the Read (RD#) signal. Read operation is initiated when this pin is pulled LOW and the chip is selected. When serial or I2C interface is selected, this pin must be connected to VSS
16~23	D0~D7	These are 8-bit bi-directional data bus to be connected to the microprocessor's data bus. When serial interface mode is selected, D0 will be the serial clock input: SCLK; D1 will be the serial data input: SDIN. When I2C mode is selected, D2, D1 should be tied together and serve as SDAout, SDAin in application and D0 is the serial clock input, SCL.
24	IREF	This is segment output current reference pin. When external IREF is used, a resistor should be connected between this pin and VSS to maintain the IREF current at a maximum of 30uA. Please refer to Figure 7-15 for the details of resistor value. When internal IREF is used, this pin should be kept NC.
25	VCOMH	Voltage Output High Level for COM Signal This pin is the input pin for the voltage output high level for COM signals. A capacitor should be connected between this pin and VSS.
26	VCC	Power Supply for OEL Panel This is the most positive voltage supply pin of the chip. A stabilization capacitor should be connected between this pin and VSS when the converter is used. It must be connected to external source when the converter is not used.
27	VLSS	This is an analog ground pin. It should be connected to VSS externally.
28	ESD GND	It should be connected to ground.

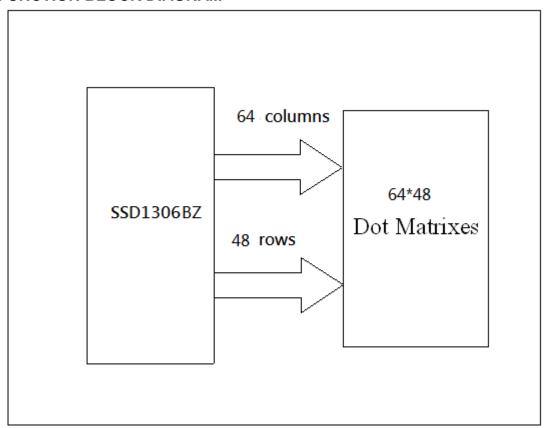


4. Contour Drawing & Block Diagram





FUNCTION BLOCK DIAGRAM



^{*}For more information, please refer to Application Note provided by Raystar Optronics.





5.Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Logic	VDD	0	4	V	1,2
Supply Voltage for Display	VCC	0	15	V	1,2
Operating Temperature	TOP	-40	+80	°C	_
Storage Temperature	TSTG	-40	+80	°C	- /

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 6 "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate



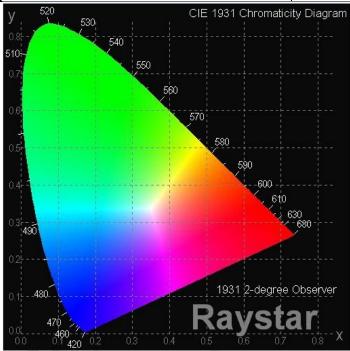
6.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage for Logic	VDD	_	2.8	3.0	3.3	V
Supply Voltage for Display	VCC	_	7.0	7.25	7.5	٧
Input High Volt.	VIH	_	0.8×VDD	-<	VDDIO	V
Input Low Volt.	VIL	_	0	-	0.2×VDD	V
Output High Volt.	VOH	_	0.9×VDD	+>	VDDIO	V
Output Low Volt.	VOL	_	0	_	0.1×VDD	V
50% Check Board operating Current	ICC	VCC=7.25V	->	6.0	13.0	mA



7. Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V)θ	_	160	_	_	deg
View / wigio	(Η)φ	_	160	_		deg
Contrast Ratio	CR	Dark	2000:1	_		
Response Time	T rise	_	_	10		μs
Treespenies Times	T fall	_		10	_	μs
Display with 50% check	Board Brightnes	S	120	150	_	_
CIEx(Yellow)		x,y(CIE1931)	0.45	0.47	0.49	
CIEy(Yellow)		x,y(CIE1931)	0.48	0.50	0.52	_





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8.OLED Lifetime

ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25°C / Initial 50% check board brightness Typical Value	50,000 Hrs	-	Note

Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.



9.Reliability

Environmenta	l Test			
Test Item	Content of Test	Test Condition	Applicable Standard	
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80℃ 240hrs	, (
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-40°C 240hrs		
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80℃ 240hrs	7	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40°C 240hrs		
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60℃,90%RH 240hrs		
Temperature Cycle	Endurance test applying the low and high temperature cycle. -40°C 25°C 80°C 30min 5min 30min 1 cycle	-40°C/80°C 100 cycles		
Mechanical Tes	st			
Vibration test	Endurance test applying the vibration during transportation and using.	10~22Hz→1.5mmp-p 22~500Hz→1.5G Total 0.5hr	= 30	
Shock test	Constructional and mechanical endurance test applying the shock during transportation.	50G Half sin wave 11 ms 3 times of each direction	-0	
Atmospheric pressure test	Endurance test applying the atmospheric pressure during transportation by air.	115mbar 40hrs		
Others	1			
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330Ω CS=150pF 10 times		

^{***} Supply voltage for OLED system =Operating voltage at 25 $^{\circ}$ C



Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



10.Inspection specification

NO	Item	Criterion			AQL		
01	Electrical	1.1 Missing vertical, horizontal segment, segment contrast					
	Testing	defect.					
		1.2 Missing character , dot or icon.					
		1.3 Display malfunction.					
		1.4 No function	•	•	ada praduat ar	posifications	0.65
		1.5 Current consumption exceeds product specifications.1.6 OLED viewing angle defect.					
		1.7 Mixed produ	-	CICC	٠.		
		1.8 Contrast def	, , , , , , , , , , , , , , , , , , ,				
		1.0 Contract defect.					
02	Black or					mm, no more than	
	white	three white or bl					
	spots on	2.2 Densely spa	ced: No m	ore	than two spots	s or lines within	2.5
	OLED (display	3mm.					
	only)					/	
03	OLED	3.1 Round type	: As				
	black	following drawin			SIZE	Acceptable Q	
	spots,	$\Phi = (x + y) / 2$				TY	
	white	. X 1			Ф≦0.10	Accept no	
	spots,	→ ← +				dense	2.5
	contamina tion	• -	_ Y		0.10 <	2	2.5
	(non-displ	* *			Ф≦0.20		
	ay)				0.20 <	1	
	-3,				Ф≦0.25		
				4	0.25<Ф	0	
		3.2 Line type : (/				A (.	2
	_	(+	Length		dth	Acceptable Q TY	
		$\sim 4 \frac{W}{V}$			≤0.02	Accept no dense	2.5
		→ L 1←	L≦3.0		$02 < W \le 0.03$	2	2.0
			L≦2.5		03 <w≦0.05< td=""><td></td><td></td></w≦0.05<>		
				0.0)5 <w< td=""><td>As round type</td><td></td></w<>	As round type	
04	Polarizer						
	bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.		-	ze Ф	Acceptable Q TY	
	7				≦0.20	Accept no dense	
					20<Φ≦0.50	3	2.5
					50<Φ≦1.00	2	9,69
				1.0	00<Ф	0	
				То	tal Q TY	3 /000	



NO	Item	Criterion	AQL	
05	Scratches	Follow NO.3 OLED black spots, white spots, contamination		
		Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length:		
		6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels:		
		z: Chip thickness y: Chip width x: Chip length		
06	Chipped	Z≦1/2t Not over viewing x≦1/8a area	2.5	
00	glass	1/2t < z ≤ 2t Not exceed 1/3k x ≤ 1/8a	2.3	
		⊙If there are 2 or more chips, x is total length of each chip.6.1.2 Corner crack:		
		z: Chip thickness y: Chip width x: Chip length		
	4	Z≦1/2t Not over viewing x≦1/8a area		
		1/2t < z ≤ 2t Not exceed 1/3k x ≤ 1/8a		
		⊙ If there are 2 or more chips, x is the total length of each chip.		



NO	Item	Criterion	AQL		
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:			
		2.2.1 Only off electrode pad.			
		y: Chip width x: Chip length z: Chip thickness			
		$y \le 0.5$ mm $x \le 1/8$ a $0 < z \le t$			
		6.2.2 Non-conductive portion:			
	Olean				
06	Glass crack	12	2.5		
		X			
		y: Chip width x: Chip length z: Chip			
		$ \begin{array}{c cccc} & & \text{thickness} \\ \hline y \leq L & & x \leq 1/8a & & 0 < z \leq t \\ \end{array} $			
		⊙If the chipped area touches the ITO terminal, over 2/3 of the ITO			
		must remain and be inspected according to electrode terminal			
		specifications.			
		If the product will be heat sealed by the customer, the alignment mark not be damaged.			
		6.2.3 Substrate protuberance and internal crack.			
	-	y: width x: length			
		$y \le 1/3L$ $x \le a$			
	L	v			
			100		



NO	Item	Criterion	AQL	
07	Cracked glass	The OLED with extensive crack is not acceptable.	2.5	
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 		
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.		
10	PCB、COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down. 	2.5 2.5 0.65 2.5 2.5 0.65 2.5	
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65	



NO	Item	Criterion	AQL
12	General appearance	 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 OLED pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet. 	2.5 0.65 2.5 2.5 2.5 2.5 0.65 0.65 0.65



Check Item	Classification	Criteria			
No Display	Major				
Missing Line	Major				
Pixel Short	Major				
Darker Short	Major				
Wrong Display	Major				
Un-uniform B/A x 100% < 70% A/C x 100% < 70%	Major				
		A Normal B Dark Pixel C Light Pixel			



11.Precautions in use of OLED Modules

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, change the components or modify its shape of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Do not apply input signals while the logic power is off.
- (5) Don't operate it above the absolute maximum rating.
- (6) Don't drop, bend or twist OLED display module.
- (7) Soldering: only to the I/O terminals.
- (8) Hot-Bar FPC soldering condition: 280~350C, less than 5 seconds.
- (9) Raystar has the right to change the passive components (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.) and change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)
- (10) Raystar has the right to upgrade or modify the product function.

11.1. Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such as dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged. So, be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage by using following adhesion tape.
 - * Scotch Mending Tape No. 810 or an equivalent

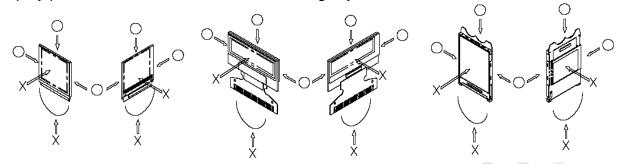
Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since the surface of the polarizer will become cloudy.

Also, pay attention that the following liquid and solvent may spoil the polarizer:

- * Water
- * Ketone
- * Aromatic Solvents
- (6) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (7) Do not touch the following sections whenever possible while handling the OLED display modules.
 - * Pins and electrodes
 - * Pattern layouts such as the TCP & FPC
- (8) Hold OLED display module very carefully when placing OLED display module into the



System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



- (9) Do not apply stress to the LSI chips and the surrounding molded sections.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
 - * Be sure to make human body grounding when handling OLED display modules.
 - * Be sure to ground tools to use or assembly such as soldering irons.
 - * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
 - * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.

11.2. Storage Precautions

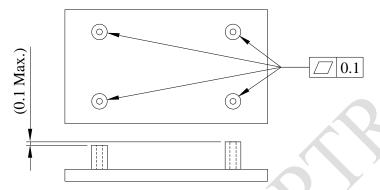
- (1) When storing OLED display modules, put them in static electricity preventive bags to avoid be directly exposed to sun or lights of fluorescent lamps. (We recommend you to store these modules in the packaged state when they were shipped from Raystar. At that time, be careful not to let water drops adhere to the packages or bags.)
- (2) When the OLED display module is being dewed or when it is placed under high temperature or high humidity environments, the electrodes may be corroded if electric current is applied. Please store it in clean environment.

11.3. Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, OLED display module may be damaged.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specification and to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD / VCC). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the nearby devices.
- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) If the power supplied to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module.
 - * Connection (contact) to any other potential than the above may lead to rupture of the IC.



- (7) If this OLED driver is exposed to light, malfunctioning may occur and semiconductor elements may change their characteristics.
- (8) The internal status may be changed, if excessive external noise enters into the module. Therefore, it is necessary to take appropriate measures to suppress noise generation or to protect module from influences of noise on the system design.
- (9) We recommend you to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.
- (10) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use the same image for long time in real application. When an OLED display module is operated for a long of time with fixed pattern, an afterimage or slight contrast deviation may occur.
- (11) The module should be fixed balanced into the housing, or the module may be twisted.



11.4. Precautions when disposing of the OLED display modules

(1) Request the qualified companies to handle industrial wastes when disposing of the OLED display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations.

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5.Others:

Page: 1 **Module Sample Estimate Feedback Sheet** Module Number: _____ 1 · Panel Specification : □NG ,____ 1. Panel Type: □ Pass □NG ,____ 2. Numbers of Pixel: □ Pass □NG ,____ 3. View Area: □ Pass □NG ,____ 4. Active Area: □ Pass □NG ,_____ 5.Emitting Color: □ Pass □NG ,__ 6.Uniformity: □Pass 7.Operating □ Pass □NG , Temperature: 8.Storage Temperature: □ Pass □NG ,____ 9.Others: 2 Mechanical Specification □NG , 1. PCB Size: □Pass □NG ,_____ 2.Frame Size: □Pass □NG ,___ 3.Materal of Frame: □Pass □NG ,___ 4.Connector Position: □Pass □NG ,____ 5.Fix Hole Position: □Pass 6. Thickness of PCB: □NG ,__ □Pass 7. Height of Frame to □Pass □NG ,____ PCB: □NG , 8.Height of Module: □Pass □NG , 9.Others: □Pass 3 Relative Hole Size: □NG ,____ 1.Pitch of Connector: □Pass 2.Hole size of □NG , □Pass Connector: □NG ,____ 3. Mounting Hole size: □Pass □Pass □NG , 4. Mounting Hole Type:

> ss □NG ,____ >> Go to page 2 <<

□Pass



		Page: 2
Module Number :		<u> </u>
4 · Electronic Characteristic	s of Modul	<u>e</u> :
1.Input Voltage:	□Pass	□NG ,
2.Supply Current:	□Pass	□NG ,
3.Driving Voltage for	□Pass	□NG ,
OLED:		
4.Contrast for OLED:	□Pass	□NG ,
5.Negative Voltage	□Pass	□NG ,
Output:		
6.Interface Function:	□Pass	□NG ,
7.ESD test:	□Pass	□NG ,
8.Others:	□Pass	□NG ,
5 · Summary :		
Sales signature :		

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for LED Displays & Accessories category:

Click to view products by Raystar manufacturer:

Other Similar products are found below:

LTC-2721WC LTC-4624JD LTC-4627G LTC-4627WC LTD-5021AWC LTM-8522G LTP-4323P LTP-747G LTS-3361JG-06

F416SYGWA/S530-E3 EADST040RA2 1668 HT-F196NB-5323 IPD2131-27 SA03-12EWA LDD-E2802RD LDD-E306MI LDQ-N514RI

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LTC-2623WC LTC-4624P LTC-4627JD LTD-2601E LTD-322G LTD-482PC LTP-1457AKR LTP-3784G-01 LTS-313AP LTS-4812SKR-P LTS-547AE LTS-6780P 446010401-3 HV-7W30-6829 CA12240_MINNIE-WWW-MTG-ASSY DA43-11GWA LDD-A516RI-17 LDD-E305RI LDQ-M513RI LDQ-M5204RI-SI LDQ-N3402RI LDQ-N3606RI LDS-A3924RI-SI